APPLICABLE STANDARD				
RATING	OPERATING TEMPERATURE RANGE	-40 °C TO +125 °C	STORAGE TEMPERATURE RANGE	-10 °C TO + 60°C (1)
	VOLTAGE	△2 60 V AC/DC	STORAGE HUMIDITY RANGE	RELATIVE HUMIDITY 85% MAX
	CURRENT	2 A		(NOT DEWED)

SPECIFICATIONS

ITEM	TEST METHOD	REQUIREMENTS	QT	AT
CONSTRUCTION				
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING.	×	×
MARKING	CONFIRMED VISUALLY.		×	×
ELECTRIC CHARACTERISTICS				
CONTACT RESISTANCE	1A DC.	10 mΩ MAX .	×	—
CONTACT RESISTANCE MILLIVOLT LEVEL METHOD	10 mV AC MAX, 0.1 mA(DC OR 1000Hz)	10 mΩ MAX .	×	—
INSULATION RESISTANCE	500 V DC.	100 MΩ MIN.	×	—
VOLTAGE PROOF	1000 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	×	—
MECHANICAL CHARACTERISTICS				
MECHANICAL OPERATION	30 TIMES INSERTIONS AND EXTRACTIONS.	① CONTACT RESISTANCE: 20 mΩ MAX. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	× ×	— —
VIBRATION	FREQUENCY 20 TO 200Hz (88m/s^2) SWEEP TIME 3min.(ROUND TRIP) AT 3h FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 7ΩMIN , 1μs MIN. ② CONTACT RESISTANCE: 20 mΩ MAX. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	× × ×	— — —
SHOCK	981m/s^2 DURATION OF PULSE 6ms AT 3 TIMES FOR 6 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 7ΩMIN , 1μs MIN. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	× ×	— —
LOCK STRENGTH	MEASURE BREAK STRENGTH OF THE LOCK BY PULLING THE CONNECTOR IN THE MATING DIRECTION.	① 100N MIN.	×	—
ENVIRONMENTAL CHARACTERISTICS				
DAMP HEAT (STEADY STATE)	EXPOSED AT 60 °C, 90 ～ 95 %, 96 h.	① CONTACT RESISTANCE: 20 mΩ MAX. ② INSULATION RESISTANCE:100 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	× × ×	— — —
RAPID CHANGE OF TEMPERATURE	TEMPERATURE- 40 →ROOM TEMP →125°C→ ROOM TEMP TIME 30 → 5 → 30 → 5 min UNDER 1000 CYCLES.	① CONTACT RESISTANCE: 20 mΩ MAX. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	× ×	— —
DRY HEAT	EXPOSED AT 140°C, 120 h.	① CONTACT RESISTANCE: 20 mΩ MAX. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	× ×	— —
COLD	EXPOSED AT -40°C , 120 h.	① CONTACT RESISTANCE: 20 mΩ MAX. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	× ×	— —
RESISTANCE TO SO_2 GAS	EXPOSED IN 25 PPM AT 75% MIN FOR 96h.	① CONTACT RESISTANCE: 20 mΩ MAX.	×	—
RESISTANCE TO SOLDERING HEAT	REFLOW TEMP. OVER 260°C , 10sec. PREHEAT 180°CMAX , 120sec.	NO PLATING PEELING OF THE TERMINALS, MELTINGS OF HOUSINGS.	×	—
SOLDERABILITY	SOLDERED AT SPECIFIED TEMPERATURE PROFILE.	A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	×	—

	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
△2	1	DIS-T-00006023	YH. MAMADA	HH. TSUKUMO	20200407

REMARK
(NOTE1) "STORAGE" means a long-term storage state for the unused product before assembly to PCB.

APPROVED	HK. UMEHARA	20171018
CHECKED	HK. UMEHARA	20171018
DESIGNED	TY. ISHIGURO	20171018
DRAWN	MN. SATOH	20171018

Note QT:Qualification Test AT:Assurance Test X:Applicable Test

DRAWING NO. ELC-368631-00-00

HRS	SPECIFICATION SHEET	PART NO.	ZE05-16DP-2H	
	HIROSE ELECTRIC CO., LTD.	CODE NO.	CL752-2105-0-00	△2 1/1

FORM HD0011-2-1